

Electronic Patent Application Fee Transmittal

| | | | | |
|---|--|-----------------|---------------|-----------------------------|
| Application Number: | 10648586 | | | |
| Filing Date: | 26-Aug-2003 | | | |
| Title of Invention: | Wafer-level chip scale package | | | |
| First Named Inventor/Applicant Name: | Efren M. Lacap | | | |
| Filer: | Philip Van Uytandaele Dizerega/Chalynda Renz | | | |
| Attorney Docket Number: | 408204 | | | |
| Filed as Small Entity | | | | |
| Utility Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Notice of appeal | 2401 | 1 | 250 | 250 |
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|-------------------|----------|----------|--------|----------------------|
| Miscellaneous: | | | | |
| Total in USD (\$) | | | | 250 |